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Claims

[c1] 1.A method of forming a printed circuit board, the method comprising the steps of:
providing a substrate comprising a seed layer formed by electroless plating;
forming a masking layer on said seed layer to provide first regions of exposed seed layer;
forming a circuit pattern on said first regions of exposed seed layer by electrolytic plating;
removing said masking layer to expose second regions of said seed layer; and
etching said exposed second regions of said seed layer with an etching liquid, said etching liquid at a temperature less than about 15 degrees Celcius.

[c2] 2.The method of claim 1, wherein the temperature of said etching liquid is about 5°C to about 10°C.

[c3] 3.The method of claim 1, wherein said masking layer comprises photoresist.

[c4] The method of claim 1, wherein said seed layer and said circuit pattern comprise copper.

[c5] The method of claim 1, wherein a distance between confronting portions of said circuit pattern is about 150μm or less.

[c6] The method of claim 1, wherein said seed layer and said circuit pattern are formed by copper plating.

[c7] The method of claim 1, wherein said etching liquid comprises an acid.

[c8] The method of claim 7, wherein said acid comprises an H_2O_2-H_2SO_4 aqueous solution.

[c9] The method of claim 1, wherein said substrate is dipped in said etching liquid within a dip bath.